

PMP10748 REV E1 Bill of Materials

| Designator | Quantity | Value | PartNumber | Manufacturer | Description | PackageReference |
|---|----------|--------|---------------------|----------------------|---|----------------------------------|
| PCB | 1 | | PMP10748 | Any | Printed Circuit Board | |
| C1, C21 | 2 | 100pF | 08055A101JAT2A | AVX | CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0805 | 0805 |
| C3in, C4, C4in, C5 | 4 | 4.7uF | GRM32ER71H475KA88L | MuRata | CAP, CERM, 4.7 μF, 50 V, +/- 10%, X7R, 1210 | 1210 |
| C8, C33 | 2 | 0.1uF | C2012X7R2A104K | TDK | Ceramic, X7R, 100V, 10% | 0805 |
| C11 | | 0.22uF | C0805C224K5RACTU | Kemet | CAP, CERM, 0.22 µF, 50 V, +/- 10%, X7R, 0805 | 0805 |
| C55 | 1 | 220uF | EEE-FC1H221P | Panasonic | CAP, AL, 220 µF, 50 V, +/- 20%, 0.3 ohm, SMD | SMT Radial G |
| C56 | 1 | 1000uF | EEV-FK1H102M | Panasonic | CAP, AL, 1000 μF, 50 V, +/- 20%, 0.073 ohm, SMD | SMT Radial J16 |
| DRV1, DRV2, DRV3, H1, H2, Output, Output, VIN1, VIN2 | 9 | Red | 5010 | Keystone | Test Point, Multipurpose, Red, TH | Red Multipurpose Testpoint |
| EN | 1 | Double | 1503-2 | Keystone Electronics | Terminal, Turret, TH, Double | |
| FET1_B, FET2_B, FET3_A | 3 | 40V | SQJ422EP-T1-GE3 | Vishay-Siliconix | MOSFET, N-CH, 40 V, 75 A, PowerPAK_SO-8L | PowerPAK_SO-8L |
| GND1, GND2, GNDout | 3 | Black | 5011 | Keystone | Test Point, Multipurpose, Black, TH | Black Multipurpose Testpoint |
| GND, J4 | 2 | | 6092 | Keystone | Standard Banana Jack, Insulated, Black | 6092 |
| H1, H2, H3, H4 | 4 | | NY PMS 440 0025 PH | B&F Fastener Supply | Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead | Screw |
| H5, H6, H7, H8 | 4 | | 1902C | Keystone | Standoff, Hex, 0.5"L #4-40 Nylon | Standoff |
| H9, H10, H11, H12 | 4 | | SJ-5303 (CLEAR) | 3M | Bumpon, Hemisphere, 0.44 X 0.20, Clear | Transparent Bumpon |
| J3, VBAT_1, VBAT_2 | 3 | | 6091 | Keystone | Standard Banana Jack, Insulated, Red | 6091 |
| L1, L2 | 2 | White | 5012 | Keystone | Test Point, Multipurpose, White, TH | White Multipurpose Testpoint |
| R2 | 1 | 240k | CRCW0805240KJNEA | Vishay-Dale | RES, 240 k, 5%, 0.125 W, 0805 | 0805 |
| R3 | 1 | 14.0k | CRCW080514K0FKEA | Vishay-Dale | RES, 14.0 k, 1%, 0.125 W, 0805 | 0805 |
| R4 | 1 | 4.99k | CRCW12064K99FKEA | Vishay-Dale | RES, 4.99 k, 1%, 0.25 W, 1206 | 1206 |
| R5 | 1 | 0 | CRCW06030000Z0EA | Vishay-Dale | 5%, 0.1W | 0603 |
| R6 | 1 | 100k | CRCW0603100kFKEA | Vishay-Dale | 1%, 0.1W | 0603 |
| Ru | 1 | 0 | CRCW08050000Z0EA | Vishay-Dale | RES, 0, 5%, 0.125 W, 0805 | 0805 |
| STATUS | 1 | SMT | 5015 | Keystone | Test Point, Miniature, SMT | Testpoint_Keystone_ Miniature |
| TP3, TP4 | 2 | Orange | 5013 | Keystone | Test Point, Multipurpose, Orange, TH | Orange Multipurpose Testpoint |
| U1, U2 | 2 | | LM74610QDGKRQ1 | Texas Instruments | Smart Diode Controller, DGK0008A | DGK0008A |
| U3 | 1 | | LM5060Q1MM/NOPB | Texas Instruments | High-Side Protection Controller with Low Quiescent Current, 10-pin MSOP, Pb-Free | MUB10A |
| VCAP_1, VCAP_2 | 2 | 2.2uF | C2012X5R1H225K125AB | TDK | CAP, CERM, 2.2 μF, 50 V, +/- 10%, X5R, 0805 | 0805 |
| FET1_A, FET2_A | 0 | 40V | CSD18501Q5A | Texas Instruments | MOSFET, N-CH, 40 V, 22 A, SON 5x6mm | SON 5x6mm |
| FID1, FID2, FID3 | 0 | | N/A | N/A | Fiducial mark. There is nothing to buy or mount. | Fiducial |
| Q1 | 0 | 100V | SUM40N10-30 | Vishay-Siliconix | 40A, 35nC, rDS(on) @ 4.5V = | DDPAK |
| Ro | 0 | 0 | CRCW08050000Z0EA | Vishay-Dale | RES, 0, 5%, 0.125 W, 0805 | 0805 |

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